

To our customers,

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## Old Company Name in Catalogs and Other Documents

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Renesas Electronics website: <http://www.renesas.com>

April 1<sup>st</sup>, 2010  
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (<http://www.renesas.com>)

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**1 310 nm InGaAsP MQW-FP LASER DIODE  
COAXIAL MODULE FOR OTDR APPLICATION**

**DESCRIPTION**

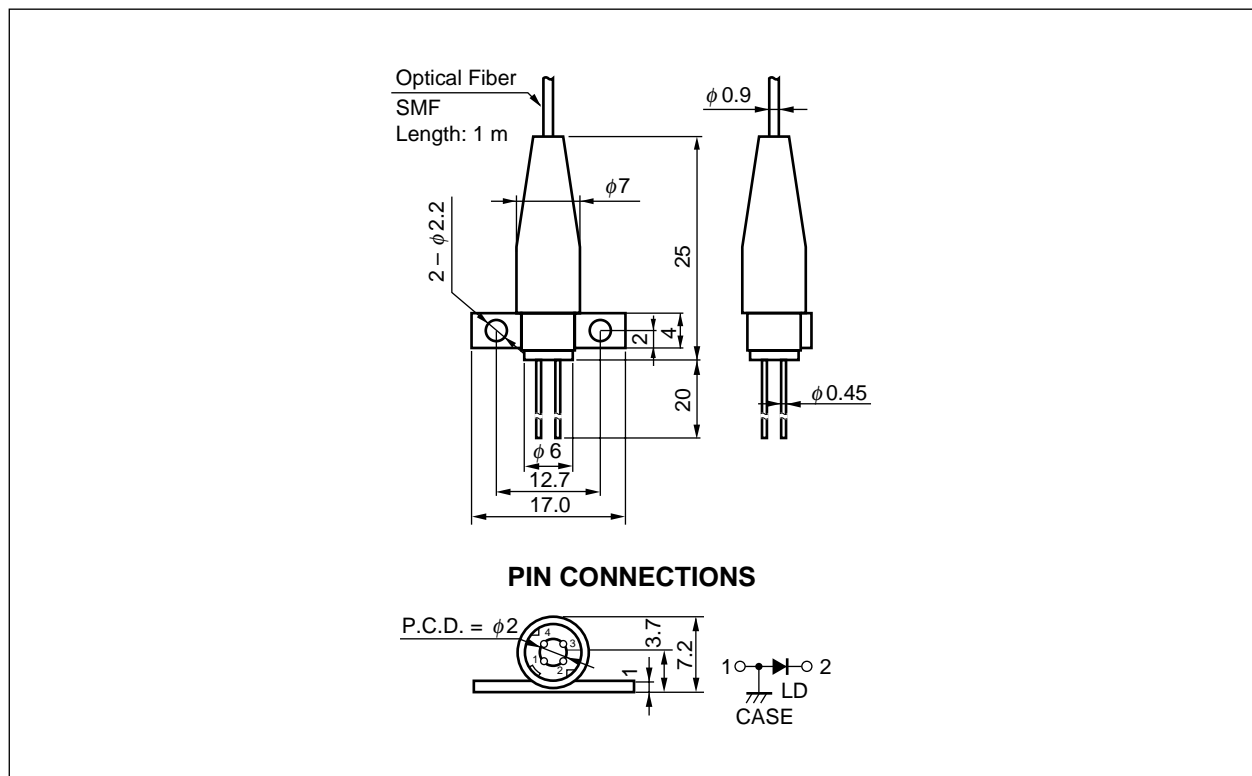
The NX7329BB-AA is a 1 310 nm Multiple Quantum Well (MQW) structured Fabry-Perot (FP) laser diode coaxial module with single mode fiber. This module is specified to operate under pulsed condition and designed for light source of Optical Time Domain Reflectometer (OTDR).

**FEATURES**

- High output power  $P_r = 50 \text{ mW} @ I_{FP} = 400 \text{ mA}^{*1}$
- Long wavelength  $\lambda_c = 1\,310 \text{ nm}$

\*1 Pulse Conditions: Pulse width (PW) = 10  $\mu\text{s}$ , Duty = 1%

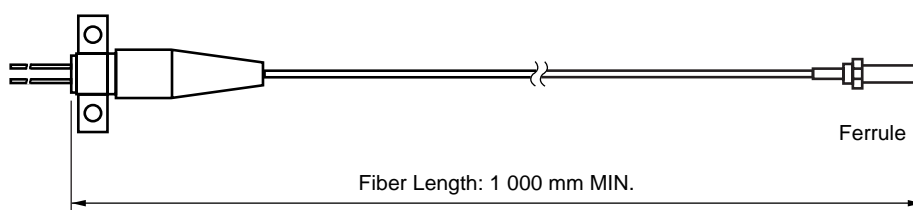
**PACKAGE DIMENSIONS (UNIT: mm)**



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# OPTICAL FIBER CHARACTERISTICS

Parameter	Specification	Unit
Mode Field Diameter	9.3±0.5	μm
Cladding Diameter	125±2	μm
Maximum Cladding Noncircularity	2	%
Maximum Core/Cladding Concentricity	1.6	%
Outer Diameter	0.9±0.1	mm
Cut-off Wavelength	1 140 to 1 280	nm
Minimum Fiber Bending Radius	30	mm
Fiber Length	1 000 MIN.	mm



# ORDERING INFORMATION

Part Number	Flange Type
NX7329BB-AA	flat mount flange

# ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Ratings	Unit
Pulsed Forward Current <sup>*1</sup>	$I_{FP}$	600	mA
Reverse Voltage	$V_R$	2.0	V
Operating Case Temperature	$T_C$	-20 to +60	°C
Storage Temperature	$T_{stg}$	-40 to +85	°C
Lead Soldering Temperature	$T_{slid}$	260 (10 sec.)	°C
Relative Humidity (noncondensing)	RH	85	%

\*1 Pulse Condition: Pulse Width (PW) = 10  $\mu$ s, Duty = 1%

# ELECTRO-OPTICAL CHARACTERISTICS ( $T_C = 25^\circ\text{C}$ )

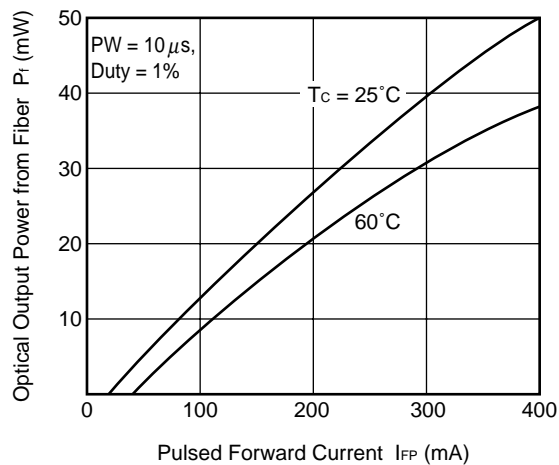
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Forward Voltage	$V_{FP}$	$I_{FP} = 400\text{ mA}$ , PW = 10 $\mu$ s, Duty = 1%		2.5	4.0	V
Threshold Current	$I_{th}$			20	30	mA
Optical Output Power from Fiber	$P_f$	$I_{FP} = 400\text{ mA}$ , PW = 10 $\mu$ s, Duty = 1%	25	50		mW
Center Wavelength	$\lambda_C$	RMS (-20 dB), $I_{FP} = 400\text{ mA}$ , PW = 10 $\mu$ s, Duty = 1%	1 290	1 310	1 330	nm
Spectral Width	$\sigma$	RMS (-20 dB), $I_{FP} = 400\text{ mA}$ , PW = 10 $\mu$ s, Duty = 1%		4.5	10.0	nm
Rise Time	$t_r$	10-90%			1.0	ns
Fall Time	$t_f$	90-10%			1.0	ns

# ELECTRO-OPTICAL CHARACTERISTICS ( $T_C = 0\text{ to }+60^\circ\text{C}$ )

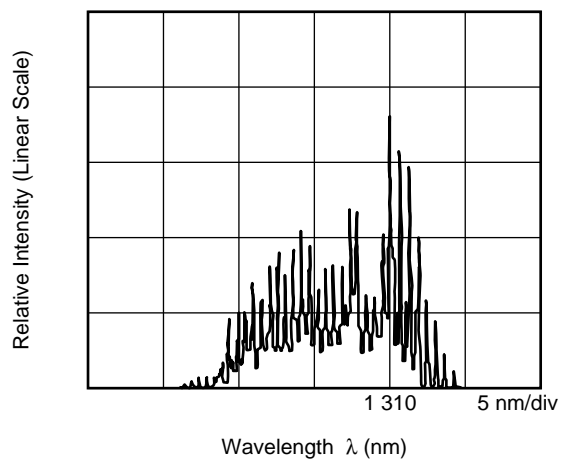
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Threshold Current	$I_{th}$				50	mA
Optical Output Power from Fiber	$P_f$	$I_{FP} = 400\text{ mA}$ , PW = 10 $\mu$ s, Duty = 1%	15			mW
Center Wavelength	$\lambda_C$	RMS (-20 dB), $I_{FP} = 400\text{ mA}$ , PW = 10 $\mu$ s, Duty = 1%	1 280		1 342.5	nm
Temperature Dependency of Center Wavelength	$\Delta\lambda/\Delta T$			0.35		nm/°C
Spectral Width	$\sigma$	RMS (-20 dB), $I_{FP} = 400\text{ mA}$ , PW = 10 $\mu$ s, Duty = 1%			10	nm

**TYPICAL CHARACTERISTICS ( $T_c = 25^\circ\text{C}$ , unless otherwise specified)**

OPTICAL OUTPUT POWER FROM FIBER vs. PULSED FORWARD CURRENT



SPECTRUM



**Remark** The graphs indicate nominal characteristics.

OTDR LD FAMILY

Part Number	Electro-Optical Characteristics (T <sub>c</sub> = 25°C)			Conditions			Application	Package
	$\lambda_c$ (nm)	P <sub>f</sub> (mW)		I <sub>FP</sub> (mA)	PW ( $\mu$ s)	Duty (%)		
	TYP.	MIN.	TYP.					
NX7327BF-AA	1 310	110	180	1 000	10	1	OTDR	4-pin coax. with SMF
NX7328BF-AA	1 310	70	110	400	10	1	OTDR	4-pin coax. with SMF
NX7329BB-AA	1 310	25	50	400	10	1	OTDR	4-pin coax. with SMF
NX7526BF-AA	1 550	95	145	1 000	10	1	OTDR	4-pin coax. with SMF
NX7527BF-AA	1 550	120	145	1 000	10	1	OTDR	4-pin coax. with SMF
NX7528BF-AA	1 550	60	80	400	10	1	OTDR	4-pin coax. with SMF
NX7529BB-AA	1 550	20	40	400	10	1	OTDR	4-pin coax. with SMF

**REFERENCE**

Document Name	Document No.
Optical semiconductor devices for fiberoptic communications Selection Guide	P12480E
Opto-Electronics Devices Pamphlet	P13623E
Opto-Electronics Devices (CD-ROM)	P12944X
NEC semiconductor device reliability/quality control system <sup>*1</sup>	C11159E
Quality grades on NEC semiconductor devices <sup>*1</sup>	C11531E
SEMICONDUCTOR SELECTION GUIDE –Products and Packages– <sup>*1</sup>	X13769E

<sup>\*1</sup> Published by NEC Corporation

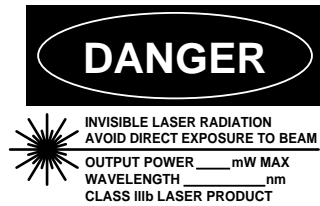


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M8E 00.4-0110

**SAFETY INFORMATION ON THIS PRODUCT**



**SEMICONDUCTOR LASER**



**AVOID EXPOSURE-Invisible**  
Laser Radiation is emitted from  
this aperture

<b>Warning</b>	Laser Beam	<p>A laser beam is emitted from this diode during operation. The laser beam, visible or invisible, directly or indirectly, may cause injury to the eye or loss of eyesight.</p> <ul style="list-style-type: none"> <li>• Do not look directly into the laser beam.</li> <li>• Avoid exposure to the laser beam, any reflected or collimated beam.</li> </ul>
<b>Caution</b>	GaAs Products	<p>The product contains gallium arsenide, GaAs. GaAs vapor and powder are hazardous to human health if inhaled or ingested.</p> <ul style="list-style-type: none"> <li>• Do not destroy or burn the product.</li> <li>• Do not cut or cleave off any part of the product.</li> <li>• Do not crush or chemically dissolve the product.</li> <li>• Do not put the product in the mouth.</li> </ul> <p>Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.</p>
<b>Caution</b>	Optical Fiber	<p>A glass-fiber is attached on the product. Handle with care.</p> <ul style="list-style-type: none"> <li>• When the fiber is broken or damaged, handle carefully to avoid injury from the damaged part or fragments.</li> </ul>

► **Business issue**

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► **Technical issue**

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